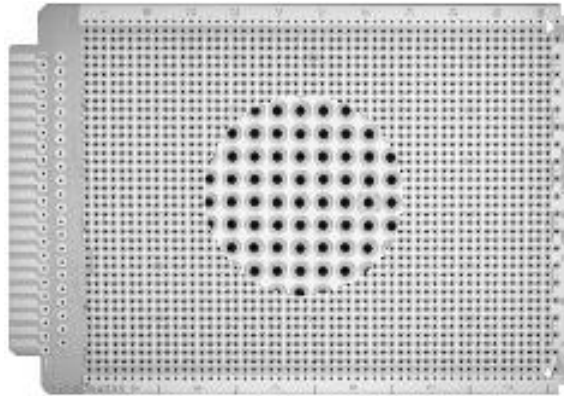


**3662**

**4.5" x 6.5"**

**Circuit Pattern:** Contacts Only  
**Contacts:** 22/44 @ .156 Ctrs, Ni/Gold  
**Width/Thick:** 6.50"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 50  
**Material:** CEM-1.  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Solder Connector:** R644  
**Extender:** 3690  
**Rec. Card Cage:** Series 13  
**Wire-Wrap Connector:** R644-3  
**Hole Diameter:** .042"

- Unrestricted component placement over entire board surface
- Layout paper and instructions included
- Row and column legend provided

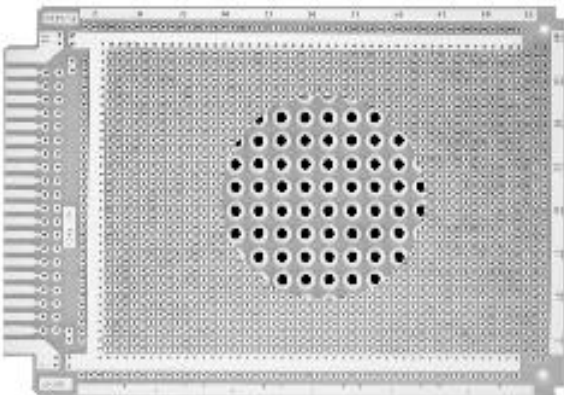


**3662A6**

**4.5" x 6.5"**

**Circuit Pattern:** Ground Plane  
**Contacts:** 22/44 @ .156" Ctrs, Ni/Gold  
**Width/Thick:** 6.50"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 90  
**Material:** CEM-1 .  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Solder Connector:** R644  
**Extender:** 3690  
**Rec. Card Cage:** Series 13  
**Wire-Wrap Connector:** R644-3  
**Hole Diameter:** .042"

- 0.085" diameter clearance area around holes
- Ground plane on component side; wiring side has contacts only
- To commit wire-wrap pins to ground planes, use Vector T124 solder washers, available separately
- Plane surface is solder-coated for user convenience
- Layout paper and instructions included
- Row and column legend provided

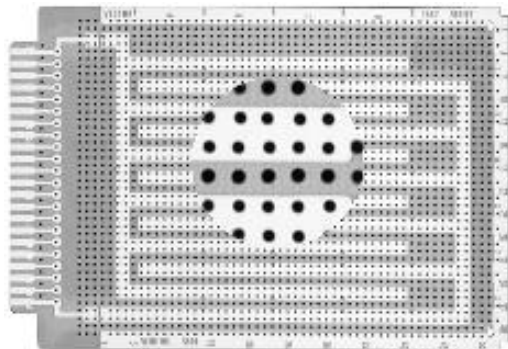


**3662-9**

**4.5" x 6.5"**

**Circuit Pattern:** Pad-Per-Hole  
**Contacts:** 22/44 @ .156" Ctrs, Ni/Gold  
**Width/Thick:** 6.50"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 48  
**Material:** FR4 Epoxy Glass  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Solder Connector:** R644  
**Extender:** 3690  
**Rec. Card Cage:** Series 13  
**Wire-Wrap Connector:** R644-3  
**Hole Diameter:** .042"

- 0.080" diameter, isolated solder pad around holes, both sides
- Pad and bus surfaces solder-coated for quick, convenient soldering
- Row and column legends provided
- Layout paper and instructions included



**3682-2**

**4.5" x 6.5"**

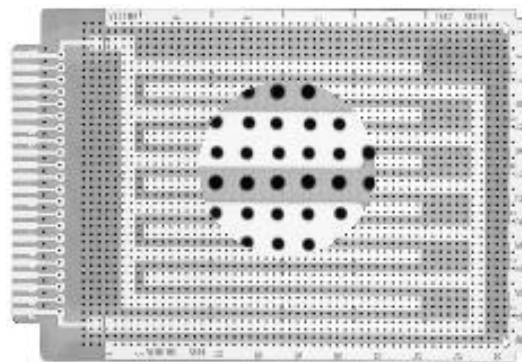
**Circuit Pattern:** Interleaved Buses  
**Contacts:** 22/44 @ .156" Ctrs, Ni/Gold  
**Width/Thick:** 6.50"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 24  
**Material:** CEM-1  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Solder Connector:** R644  
**Extender:** 3690  
**Rec. Card Cage:** Series 13  
**Wire-Wrap Connector:** R644-3  
**Hole Diameter:** .042"

- Bus pattern on wiring side, solder-coated for user convenience
- Bus outline traced on component side to facilitate component placement
- Mounts DIPs with 0.3", 0.4" and 0.9" lead spacing
- Unclad test point area at top of board
- Layout paper and instructions included
- Row and column legends provided

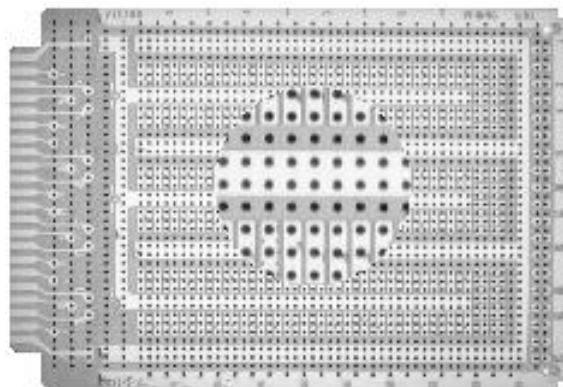
**Note:** Same as 3682-4 but without Ground Plane

**3682-4 4.5" x 6.5"**

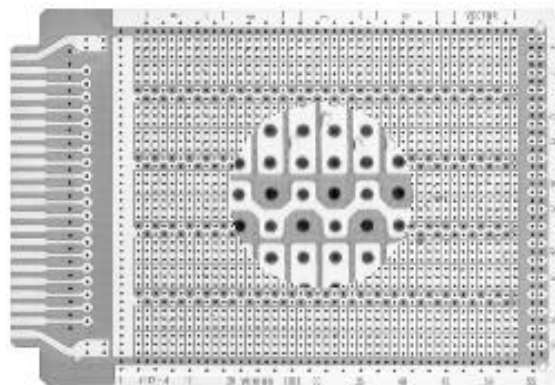
<b>Circuit Pattern:</b>	Interleaved Bus/ Ground Plane	<ul style="list-style-type: none"> <li>• Power bus in rows across component side; overall ground plane on wiring side</li> <li>• 0.085" etched clearance area around each hole on ground plane side</li> <li>• Bus and plane surfaces solder coated for user convenience</li> <li>• To commit wire-wrap pins to ground planes, use Vector T124 solder washers, available separately</li> <li>• Layout paper and instructions included</li> <li>• Row and column legends provided</li> </ul>
<b>Contacts:</b>	22/44 @ .156" Ctrs, Ni/Gold	
<b>Width/Thick:</b>	6.50"/.062"	
<b>Height:</b>	4.50"	
<b>16-Pin DIP Capacity:</b>	24	
<b>Material:</b>	CEM-1	
<b>Wire-Wrap Terminals:</b>	T44, T46, T49, T68	
<b>Wire-Wrap Socket Pins:</b>	R32	
<b>Solder Connector:</b>	R644	
<b>Extender:</b>	3690	
<b>Rec. Card Cage:</b>	Series 13	
<b>Wire-Wrap Connector:</b>	R644-3	
<b>Hole Diameter:</b>	.042"	

**3677-2 4.5" x 6.5"**

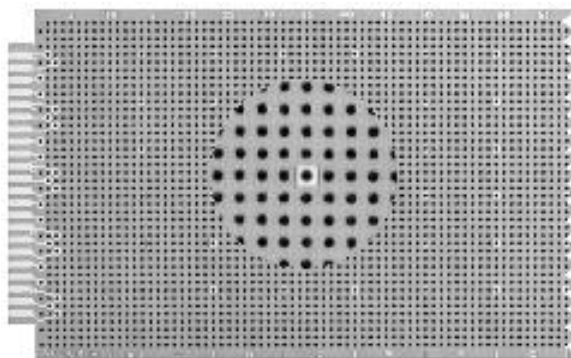
<b>Circuit Pattern:</b>	3-Hole Solder Pad	<ul style="list-style-type: none"> <li>• 3-hole solder pads (0.28" x 0.080") for interconnecting multiple component leads</li> <li>• Voltage/ground buses interleaved between pad areas on wiring side</li> <li>• Row and column legends provided</li> <li>• Test point area, with solder pads around holes, provided along back edge of board</li> <li>• Layout paper and instructions included</li> </ul>
<b>Contacts:</b>	22/44 @ .156" Ctrs. Ni/Gold	
<b>Width/Thick:</b>	6.50"/.062"	
<b>Height:</b>	4.50"	
<b>16-Pin DIP Capacity:</b>	12	
<b>Material:</b>	CEM-1	
<b>Wire-Wrap Terminals:</b>	T44, T46, T49, T68	
<b>Wire-Wrap Socket Pins:</b>	R32	
<b>Solder Connector:</b>	R644	
<b>Extender:</b>	3690	
<b>Rec. Card Cage:</b>	Series 13	
<b>Wire-Wrap Connector:</b>	R644-3	
<b>Hole Diameter:</b>	.042"	

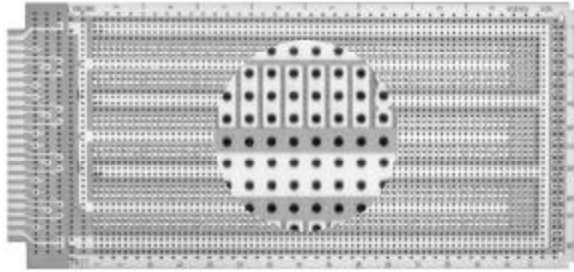
**4112-4 4.5" x 6.5"**

<b>Circuit Pattern:</b>	3-Hole Solder Pad	<ul style="list-style-type: none"> <li>• Continuous ground plane on component side with 0.085" clearance pad around each hole</li> <li>• 3-hole solder pads (0.28 x 0.080") for interconnecting multiple component leads</li> <li>• Row and column legends provided</li> <li>• Layout paper and instructions included</li> </ul>
<b>Contacts:</b>	22/44 @ .156" Ctrs, Ni/Gold	
<b>Width/Thick:</b>	6.50"/.062"	
<b>Height:</b>	4.50"	
<b>16-Pin DIP Capacity:</b>	25	
<b>Material:</b>	CEM-1	
<b>Wire-Wrap Terminals:</b>	T44, T46, T49, T68	
<b>Wire-Wrap Socket Pins:</b>	R32	
<b>Solder Connector:</b>	R644	
<b>Extender:</b>	3690	
<b>Rec. Card Cage:</b>	Series 13	
<b>Wire-Wrap Connector:</b>	R644-3	
<b>Hole Diameter:</b>	.042"	

**3662-2 4.5" x 9.6"**

<b>Circuit Pattern:</b>	Contacts Only	<ul style="list-style-type: none"> <li>• Unrestricted component placement over entire board surface</li> <li>• Row and column legends provided</li> <li>• Layout paper and instructions included</li> </ul>
<b>Contacts:</b>	22/44 @ .156" Ctrs, Ni/Gold	
<b>Width/Thick:</b>	9.60"/.062"	
<b>Height:</b>	4.50"	
<b>16-Pin DIP Capacity:</b>	90	
<b>Material:</b>	CEM-1	
<b>Wire-Wrap Terminals:</b>	T44, T46, T49, T68	
<b>Wire-Wrap Socket Pins:</b>	R32	
<b>Solder Connector:</b>	R644	
<b>Extender:</b>	3690-6	
<b>Rec. Card Cage:</b>	Series 14	
<b>Wire-Wrap Connector:</b>	R644-3	
<b>Hole Diameter:</b>	.042"	



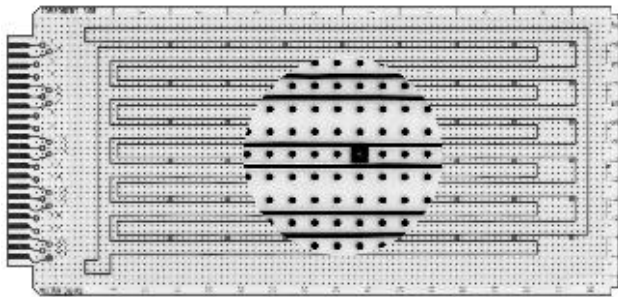


### 3677

**Circuit Pattern:** 3-Hole Solder Pad  
**Contacts:** 22/44 @ .156" Ctrs., Ni/Gold  
**Width/Thick:** 9.60"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 21  
**Material:** CEM-1  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Solder Connector:** R644  
**Extender:** 3690  
**Rec. Card Cage:** Series 14  
**Wire-Wrap Connector:** R644-3  
**Hole Diameter:** .042"

### 4.5" x 9.6"

- 3-hole solder pads (0.28" x 0.080") for interconnecting multiple component leads
- Row and column legends provided
- Layout paper and instructions included

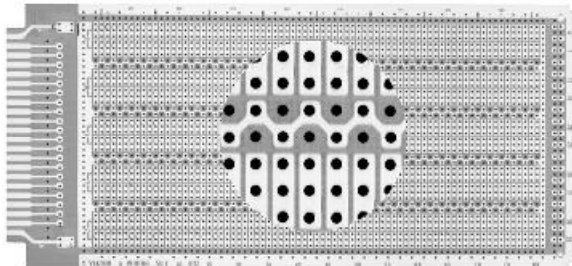


### 3682

**Circuit Pattern:** Interleaved Buses  
**Contacts:** 22/44 @ .156 Ctrs., Ni/Gold  
**Width/Thick:** 9.60"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 48  
**Material:** CEM-1  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Solder Connector:** R644  
**Extender:** 3690-6  
**Rec. Card Cage:** Series 13  
**Wire-Wrap Connector:** R644-3  
**Hole Diameter:** .042"

### 4.5" x 9.6"

- Etched bus pattern on wiring side, solder-coated for user convenience
- Bus outlines traced on component side
- Mounts DIPs with 0.3", 0.4" and 0.9" lead spacings
- Layout paper and instructions included
- Row and column legends provided



### 4112

**Circuit Pattern:** 3-Hole Solder Pad  
**Contacts:** 22/44 @ .156" Ctrs., Ni/Gold  
**Width/Thick:** 9.60"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 40  
**Material:** FR4 Epoxy Glass  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Solder Connector:** R644  
**Extender:** 3690-6  
**Rec. Card Cage:** Series 13  
**Wire-Wrap Connector:** R644-3  
**Hole Diameter:** .042"

### 4.5" x 9.6"

- Zig-zag bus pattern on wiring side provides access to voltage or ground at alternating hole positions
- 3-hole solder pads (0.28" x 0.080") for interconnecting multiple component leads
- Continuous ground plane on component side with 0.085" etched clearance area around each hole
- Layout paper and instructions included
- Row and column legends provided



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

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